

ABSTRACT

GRINDING WHEEL AND GRINDING APPARATUS

A grinding wheel for grinding a wafer held on a holding table includes: a first circular annular plate mounted to a mount of a grinding apparatus; a tubular body extending downward from an outer circumference of the first circular annular plate; a second circular annular plate connected to a lower end of the tubular body; a plurality of grindstones arranged in an annular pattern on a lower surface of the second circular annular plate; an annular ultrasonic oscillation section disposed on an upper surface of the second circular annular plate so as to surround an opening; and an ultrasonic reception section that receives an ultrasonic vibration transmitted from the ultrasonic oscillation section to the grindstones.

(Figure 4A)